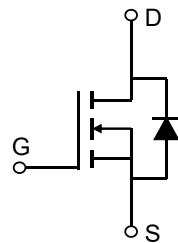


Description

Features

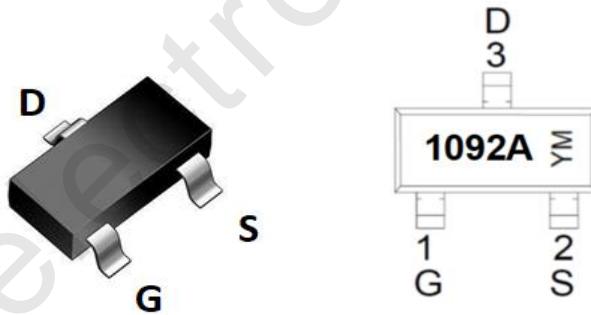
- 100V, 3.5A
- $R_{DS(ON)}$ Typ = 93mΩ @ V_{GS} = 10V
- $R_{DS(ON)}$ Typ = 113mΩ @ V_{GS} = 4.5V
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMJGL1092A	1092A	SOT-23-3L	TAPING	7"	3000	120000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	3.5	A
		2.1	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	14	A
P_D	Power Dissipation	3.1	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾	40.3	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	1.1	1.6	2.2	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 10\text{V}, I_D = 3\text{A}$	-	93	121	$\text{m}\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 1\text{A}$	-	113	147	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance		-	144	-	pF
C_{oss}	Output Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 50\text{V}, f = 1\text{MHz}$	-	40	-	pF
C_{rss}	Reverse Transfer Capacitance		-	3	-	pF
Q_g	Total Gate Charge		-	4	-	nC
Q_{gs}	Gate Source Charge	$V_{GS} = 0 \text{ to } 10\text{V}$	-	0.9	-	nC
Q_{gd}	Gate Drain("Miller") Charge	$V_{DS} = 50\text{V}, I_D = 3\text{A}$	-	1.1	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On DelayTime		-	13	-	ns
t_r	Turn-On Rise Time	$V_{GS} = 10\text{V}, V_{DD} = 50\text{V}$	-	19	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D = 3\text{A}, R_{\text{GEN}} = 3\Omega$	-	20	-	ns
t_f	Turn-Off Fall Time		-	28	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	3.5	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	14	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 3\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	30	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F = 3\text{A}, dI/dt = 100\text{A/us}$	-	37	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

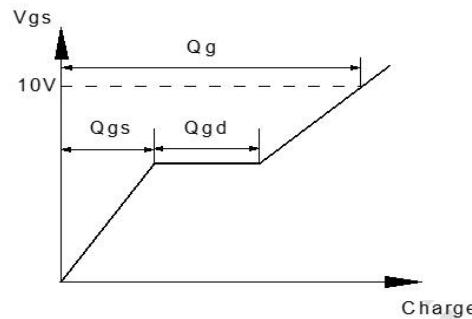
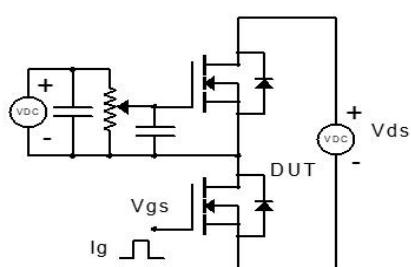


Figure 1: Gate Charge Test Circuit & Waveform

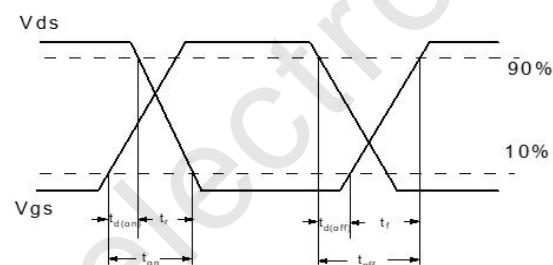
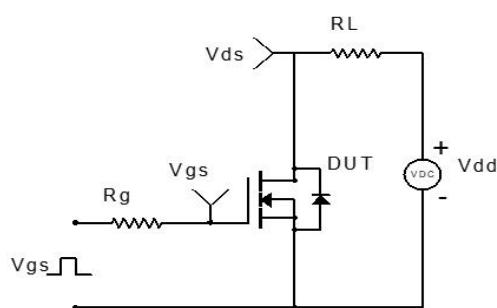


Figure 2: Resistive Switching Test Circuit & Waveform

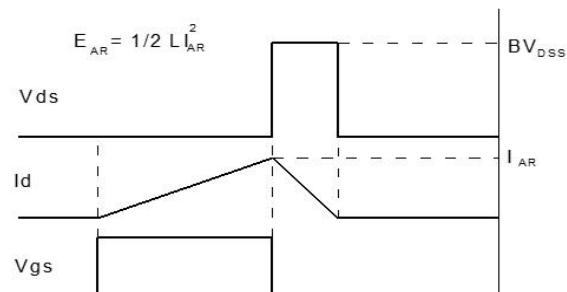
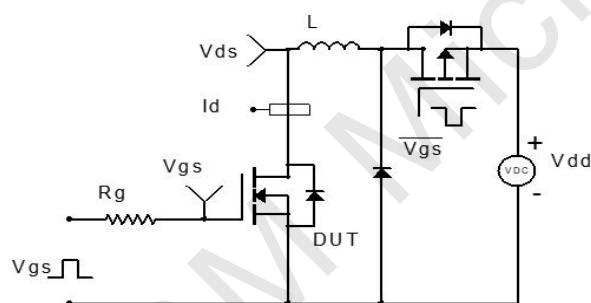


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

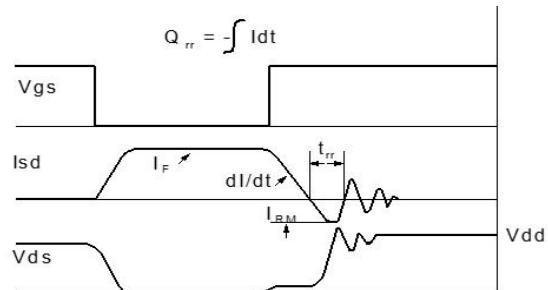
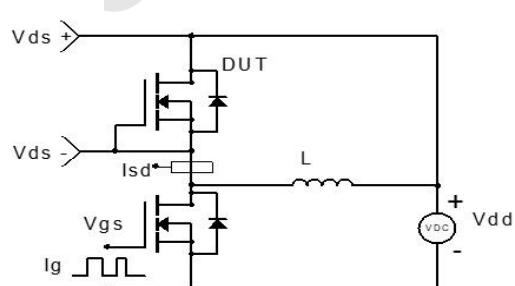
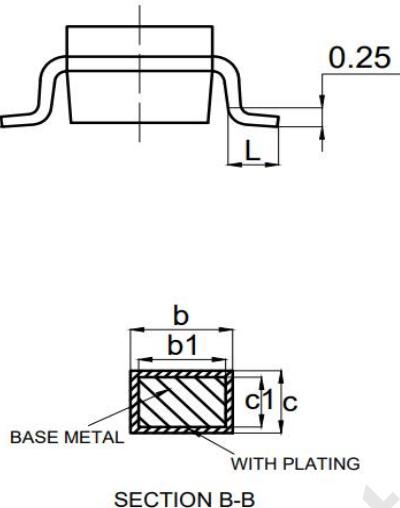
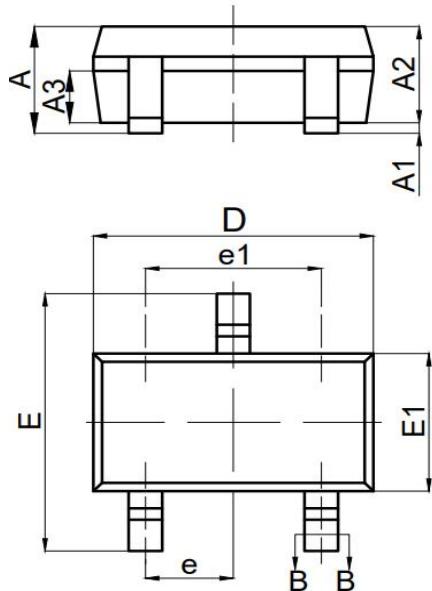


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23-3L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.25
A1	0.04	—	0.10
A2	1.00	1.10	1.20
A3	0.55	0.65	0.75
b	0.30	—	0.40
b1	0.37	0.40	0.43
c	0.11	—	0.21
c1	0.10	0.13	0.16
D	2.72	2.92	3.12
E	2.60	2.80	3.00
E1	1.40	1.60	1.80
e	—	0.95BSC	—
e1	—	1.90BSC	—
L	0.30	—	0.60
Ø	0	—	8°

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